



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20251119002.1

**Qualify Clark as an additional Assembly/Test site for specific UxQFN devices
Change Notification / Sample Request**

Date: November 19, 2025
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20251119002.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
SN74AXC1T45DTQR	SN74AXC1T45DTQR
SN74AXC2T45DTMR	NULL
SN74LXC2T45DTMR	NULL
TXU0202DTMR	NULL
TXU0101DTQR	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20251119002.1		PCN Date:	November 19, 2025	
Title:	Qualify Clark as an additional Assembly/Test site for specific UxQFN devices				
Customer Contact:	Change Management team		Dept:	Quality Services	
Proposed 1 st Ship Date:	February 17, 2026		Sample requests accepted until:	January 18, 2026*	
*Sample requests received after January 18, 2026 will not be supported.					
Change Type:					
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material
<input checked="" type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>	Mechanical Specification	<input checked="" type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Material
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of TI Clark as an additional Assembly/Test site for the list of devices shown below. Material differences between sites are as follows.

UxQFN Build Sites	
Assembly Sites	ATXSZ, CARZAT, CDAT, TIEMA, Clark
Mount Compound	SID#1500257101
	SID#1400336111
	4224819
	4226215
	4223179
Mold Compound	SID#1801512111
	4222198
	8095374
Lead frame Finish	NIPDAU, Sn
Bond Wire (mil)	AU (0.7), CU (0.8)

This notice is to communicate an update in CDAT & Clark device symbolization format for the devices in the product affected selection as follows:

	ATXSZ, CARZAT, TIEMA	CDAT, Clark
Topside Marking	Pin 1 = 0 with indicator of yearly quarter of build	Pin 1 = 0 only

Qual details are provided in the Qual Data Section.
 Test coverage, insertions, conditions will remain consistent with current testing.

Reason for Change:

Continuity of supply.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None.

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change

Changes to product identification resulting from this PCN:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
ATXSZ	ASN	CHN	Suzhou
CARZAT	CSZ	CHN	Jiangsu
CDAT	CDA	CHN	Chengdu
TIEMA	CU6	MYS	Melaka
TI Clark	QAB	PHL	Pampanga

Sample product shipping label (not actual product label)


TEXAS INSTRUMENTS
 MADE IN: Malaysia
 2DC: 20:


G4



(1P) **SN74LS07NSR**
 (Q) **2000** (D) **0336**
 (31T) LOT: 3959047MLA
 (4W) TKY (1T) 7523483SI2
 (P)
 (2P) REV: (V) 0033317
 (20L) CS0: SHE (21L) CC0:USA
 (22L) AS0: MLA (23L) ACO: MYS

MSL 2 / 260C / 1 YEAR SEAL DT
 MSL 1 / 235C / UNLIM 03/29/04
 OPT:
 ITEM: 39
LBL: 5A (L)T0:1750

Product Affected:

SN74AXC1T45DTQR	TXU0101DTQR	TXU0102DTMR
SN74AXC2T45DTMR	SN74LXC2T45DTMR	TXU0202DTMR

UxQFN Qualification Report

Data Displayed as: Number of lots / Total sample size / Total failed

	Stress Test	Duration	CLARK SN74AXC2T45DTM LSF0102DTM LSF0002DTQ LSF0101DTQ	CDAT ADS1115IRUG TLV70732DQN TMAG5231H1DQDMR
TC	Temperature Cycling -65/150C	500 Cycles	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH	96 hours	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C	1000 hours	3/231/0	-
HTSL	High Temp. Storage Bake 170C	420 hours	-	3/231/0
UHA	Unbiased HAST, 130C/85%RH	96 hours	3/231/0	-
AC	Autoclave 121C	96 hours	-	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0	3/66/0
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	CARZAT SN74AXC2T45DTM	TIEMA LM43112SN LP8549B1A SPX03 LP3971SQ-D510/NOPB DS99R4211SNG2G
TC	Temperature Cycling -65/150C	500 Cycles	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH	96 hours	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 170C	420 hours	3/231/0	3/231/0
UHA	Unbiased HAST, 130C/85%RH	96 hours	3/231/0	-
AC	Autoclave 121C	96 hours	-	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0	3/66/0
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	ASEN SN74AXC2T45DTM SN74AXC1T45DTQ
TC	Temperature Cycling -65/150C	500 Cycles	3/231/0
HAST	Biased HAST 130C/85%RH	96 hours	3/231/0
HTSL	High Temp. Storage Bake 170C	420 hours	3/231/0
UHAST	Unbiased HAST, 130C/85%RH	96 hours	3/231/0

	Stress Test	Duration	ASEN SN74AXC2T45DTM SN74AXC1T45DTQ
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0
MQ	Manufacturability	-	Pass

SN74AXC2T45DTM, SN74AXC1T45DTQ, LSF0102DTM, LSF0002DTQ, LSF0101DTQ and LP3971SQ-D510/NOPB, ADS1115IRUG, TLV70732DQW, TMAG5231H1DQDMR are qualified at MSL1. LM43112SN, LP8549B1ASPX03 are qualified at MSL2 and DS99R421ISNG2G qualified at MSL3.

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, and HTSL, as applicable

- The following are equivalent HTSL options based on activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status: Qualified Pb-Free (SMT) and Green

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF

MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.